

### IGBT Modules in ECO-PAC 2

Short Circuit SOA Capability

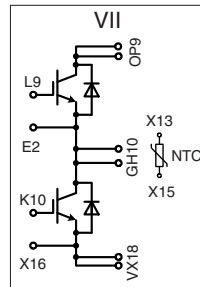
Square RBSOA

Preliminary data sheet

$$I_{C25} = 121 \text{ A}$$

$$V_{CES} = 600 \text{ V}$$

$$V_{CE(sat) \text{ typ.}} = 2.3 \text{ V}$$



Pin arrangement see outlines

#### IGBTs

Symbol	Conditions	Maximum Ratings	
$V_{CES}$	$T_{VJ} = 25^{\circ}\text{C}$ to $150^{\circ}\text{C}$	600	V
$V_{GES}$		$\pm 20$	V
$I_{C25}$	$T_C = 25^{\circ}\text{C}$	121	A
$I_{C80}$	$T_C = 80^{\circ}\text{C}$	83	A
$I_{CM}$	$V_{GE} = \pm 15 \text{ V}; R_G = 2.2 \Omega; T_{VJ} = 125^{\circ}\text{C}$ RBSOA, Clamped inductive load; $L = 100 \mu\text{H}$	200	A
$V_{CEK}$		360	V
$t_{SC}$ (SCSOA)	$V_{CE} = V_{CES}; V_{GE} = \pm 15 \text{ V}; R_G = 2.2 \Omega; T_{VJ} = 125^{\circ}\text{C}$ non-repetitive	10	$\mu\text{s}$
$P_{tot}$	$T_C = 25^{\circ}\text{C}$	379	W

#### Features

- NPT IGBT's
  - positive temperature coefficient of saturation voltage
  - fast switching
- FRED diodes
  - fast reverse recovery
  - low forward voltage
- Industry Standard Package
  - solderable pins for PCB mounting
  - isolated DCB ceramic base plate

#### Advantages

- space and weight savings
- reduced protection circuits
- leads with expansion bend for stress relief

#### Typical Applications

- AC and DC motor control
- AC servo and robot drives
- power supplies
- welding inverters

Symbol	Conditions	Characteristic Values ( $T_{VJ} = 25^{\circ}\text{C}$ , unless otherwise specified)			
		min.	typ.	max.	
$V_{CE(sat)}$	$I_C = 130 \text{ A}; V_{GE} = 15 \text{ V}; T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$		2.3 2.6	2.9 V	
$V_{GE(th)}$	$I_C = 1.5 \text{ mA}; V_{GE} = V_{CE}$	4.5		6.5 V	
$I_{CES}$	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}; T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$			1.2 7.5 mA	
$I_{GES}$	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$			400 nA	
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$ $E_{on}$ $E_{off}$	Inductive load, $T_{VJ} = 125^{\circ}\text{C}$ $V_{CE} = 300 \text{ V}; I_C = 80 \text{ A}$ $V_{GE} = 15/0 \text{ V}; R_G = 2.2 \Omega$		25 11 150 30 0.8 2.3	ns ns ns ns mJ mJ	
$C_{ies}$		$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz}$		4.2	nF
$R_{thJC}$ $R_{thJH}$		(per IGBT) with heatsink compound (0.42 K/m.K; 50 $\mu\text{m}$ )	0.66		0.33 K/W K/W

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### Reverse diodes (FRED)

Symbol	Conditions	Maximum Ratings	
$I_{F25}$	$T_C = 25^\circ\text{C}$	134.0	A
$I_{F80}$	$T_C = 80^\circ\text{C}$	82.3	A

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$V_F$	$I_F = 80\text{ A}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.85	2.06	V
		1.40		V
$I_{RM}$	$I_F = 60\text{ A}; di_F/dt = 500\text{ A}/\mu\text{s}; T_{VJ} = 125^\circ\text{C}$ $V_R = 300\text{ V}; V_{GE} = 0\text{ V}$	28		A
$t_{rr}$		100		ns
$R_{thJC}$	with heatsink compound (0.42 K/m.K; 50 $\mu\text{m}$ )	0.66		K/W
$R_{thJH}$		1.32		K/W

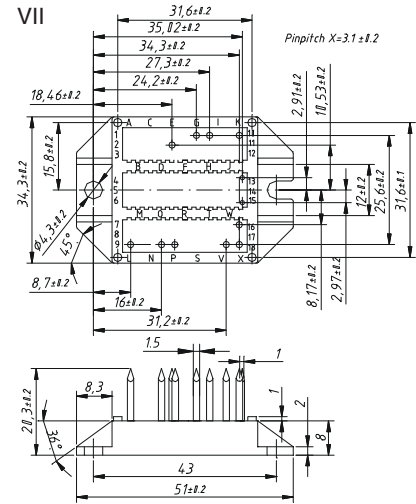
### Temperature Sensor NTC

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$R_{25}$	$T = 25^\circ\text{C}$	4.75	5.0	5.25 k $\Omega$
$B_{25/50}$		3375		K

### Module

Symbol	Conditions	Maximum Ratings	
$T_{VJ}$		-40...+150	$^\circ\text{C}$
$T_{stg}$		-40...+150	$^\circ\text{C}$
$V_{ISOL}$	$I_{ISOL} \leq 1\text{ mA}; 50/60\text{ Hz}$	3000	V~
$M_d$	mounting torque (M4)	1.5 - 2.0	Nm
		14 - 18	lb.in.
<b>a</b>	Max. allowable acceleration	50	$\text{m/s}^2$

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$d_S$	Creepage distance on surface (Pin to heatsink)	11.2		mm
$d_A$	Strike distance in air (Pin to heatsink)	11.2		mm
<b>Weight</b>		24		g



Data according to IEC 60747 and refer to a single transistor or diode unless otherwise stated.  
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